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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 462K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA, FC (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxbb5d4f35c5n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Feature	Description							
FPGA General- purpose I/Os (GPIOs)	 1.6 Gbps LVDS receiver and transmitter 800 MHz/1.6 Gbps external memory interface On-chip termination (OCT) 3.3 V support (2) 							
External Memory Interface	 Memory interfaces with low latency: Hard memory controller-up to 1.066 Gbps Soft memory controller-up to 1.6 Gbps 							
Low-power high- speed serial interface	 600 Mbps to 12.5 Gbps integrated transceiver speed Less than 105 mW per channel at 6 Gbps, less than 165 mW per channel at 10 Gbps, and less than 170 mW per channel at 12.5 Gbps Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels Physical medium attachment (PMA) with soft PCS that supports 9.8304 Gbps CPRI (Arria V GT and ST only) PMA with hard PCS that supports up to 9.8 Gbps CPRI (Arria V GZ only) Hard PCS that supports 10GBASE-R and 10GBASE-KR (Arria V GZ only) 							
HPS (Arria V SX and ST devices only)	 Dual-core ARM Cortex-A9 MPCore processor—up to 1.05 GHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, serial peripheral interface (SPI), I2C interface, and up to 85 HPS GPIO interfaces System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers On-chip RAM and boot ROM HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller ARM CoreSight™ JTAG debug access port, trace port, and on-chip trace storage 							



 $^{^{(2)}~{\}rm Arria~V~GZ}$ devices support 3.3 V with a 3.0 V ${\rm V}_{\rm CCIO}.$

Feature	Description
Configuration	 Tamper protection-comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Partial and dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8, x16, and x32 (Arria V GZ) configuration options Remote system upgrade

Arria V Device Variants and Packages

Table 3: Device Variants for the Arria V Device Family

Variant	Description
Arria V GX	FPGA with integrated 6.5536 Gbps transceivers that provides bandwidth, cost, and power levels that are optimized for high-volume data and signal-processing applications
Arria V GT	FPGA with integrated 10.3125 Gbps transceivers that provides enhanced high-speed serial I/O bandwidth for cost-sensitive data and signal processing applications
Arria V GZ	FPGA with integrated 12.5 Gbps transceivers that provides enhanced high-speed serial I/O bandwidth for high-performance and cost-sensitive data and signal processing applications
Arria V SX	SoC with integrated ARM-based HPS and 6.5536 Gbps transceivers
Arria V ST	SoC with integrated ARM-based HPS and 10.3125 Gbps transceivers

Arria V GX

This section provides the available options, maximum resource counts, and package plan for the Arria V GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

Related Information

Altera Product Selector

Provides the latest information about Altera products.



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and eighteen 10-Gbps, twelve 6-Gbps and sixteen 10-Gbps, fifteen 6-Gbps and fourteen 10-Gbps, or up to thirty-six 6-Gbps with no 10-Gbps channels.

Arria V GZ

This section provides the available options, maximum resource counts, and package plan for the Arria V GZ devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

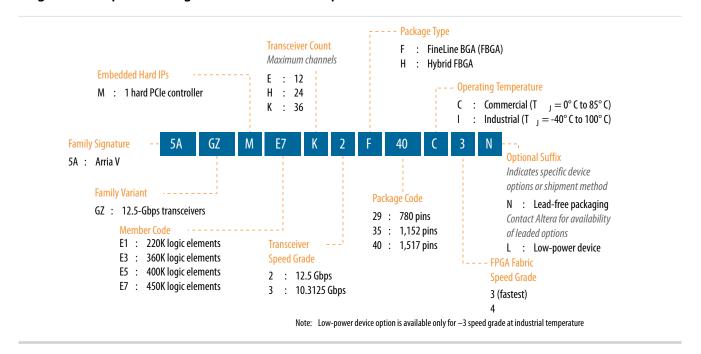
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 3: Sample Ordering Code and Available Options for Arria V GZ Devices



Maximum Resources

Table 8: Maximum Resource Counts for Arria V GZ Devices

Resource	Member Code						
nesource	E1	E 3	E 5	E 7			
Logic Elements (LE) (K)	220	360	400	450			
ALM	83,020	135,840	150,960	169,800			
Register	332,080	543,360	603,840	679,200			



Resource		Member Code						
nesc	nesource		E 3	E 5	E 7			
Memory	M20K	11,700	19,140	28,800	34,000			
(Kb)	MLAB	2,594	4,245	4,718	5,306			
Variable-pred	Variable-precision DSP Block		800 1,044		1,139			
18 x 18 Multi	18 x 18 Multiplier		2,088	2,184	2,278			
PLL	PLL		20	24	24			
12.5 Gbps Tr	ansceiver	24	24	36	36			
GPIO ⁽⁷⁾	GPIO ⁽⁷⁾		414	674	674			
LVDS	Transmitter	99	99	166	166			
LVDS	Receiver	108	108	168	168			
PCIe Hard IF	Block	1	1	1	1			

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 9: Package Plan for Arria V GZ Devices

Member Code	H780 (33 mm)		er (33 mm) (35 mm)		F1517 (40 mm)		
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	
E1	342	12	414	24	_	_	
E3	342	12	414	24	_	_	
E5	_	_	534	24	674	36	
E7	_	_	534	24	674	36	

Arria V SX

This section provides the available options, maximum resource counts, and package plan for the Arria V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.



⁽⁷⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Poss	ource	Member Code			
neso	ruice	В3	B5		
FPGA PLL		14	14		
HPS PLL		3	3		
6 Gbps Transceiver	6 Gbps Transceiver		30		
FPGA GPIO ⁽⁸⁾	FPGA GPIO ⁽⁸⁾		540		
HPS I/O	HPS I/O		208		
LVDS	Transmitter	120	120		
LVDS	Receiver	136	136		
PCIe Hard IP Block	PCIe Hard IP Block		2		
FPGA Hard Memory Controller		3	3		
HPS Hard Memory Controller		1	1		
ARM Cortex-A9 MP	Core Processor	Dual-core	Dual-core		

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 11: Package Plan for Arria V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

	F896		F896 F1152			F1517			
Member Code	r (31 mm)		(35 mm)		(40 mm)				
Code	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
В3	250	208	12	385	208	18	540	208	30
B5	250	208	12	385	208	18	540	208	30

Arria V ST

This section provides the available options, maximum resource counts, and package plan for the Arria V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.



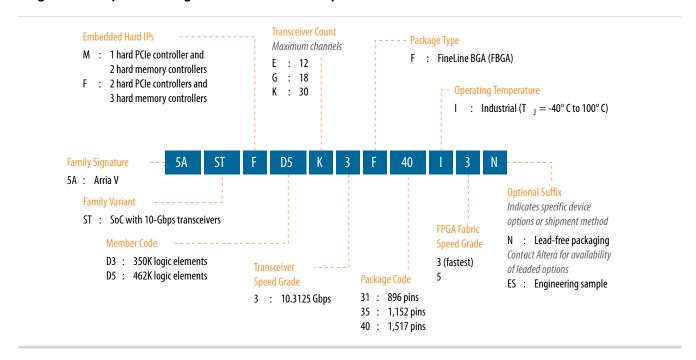
⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

Table 12: Maximum Resource Counts for Arria V ST Devices

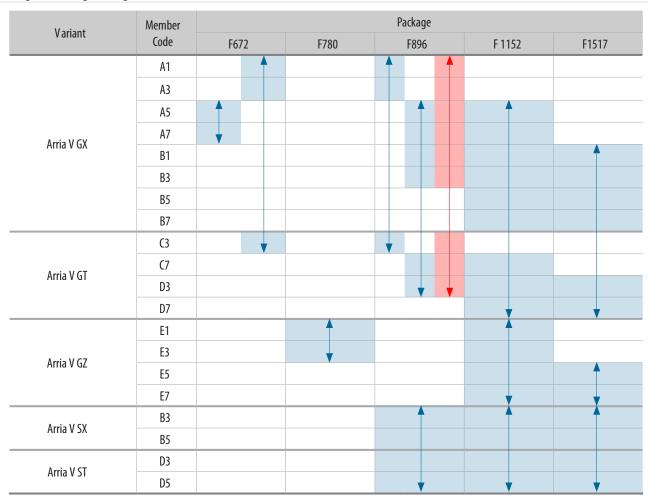
Resource		Member Code			
Reso	ource	D3	D5		
Logic Elements (LE)	Logic Elements (LE) (K)		462		
ALM		132,075	174,340		
Register	Register		697,360		
Memory (Kb)	M10K	17,290	22,820		
Memory (Rb)	MLAB	2,014	2,658		
Variable-precision D	SP Block	809	1,090		
18 x 18 Multiplier		1,618	2,180		
FPGA PLL		14	14		
HPS PLL		3	3		
Transceiver	6-Gbps	30	30		
Transcerver	10-Gbps ⁽⁹⁾	16	16		



I/O Vertical Migration for Arria V Devices

Figure 6: Vertical Migration Capability Across Arria V Device Packages and Densities

The arrows indicate the vertical migration paths. Some packages have several migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 320 GPIOs, up to nine 6 Gbps transceiver channels, and up to four 10 Gbps transceiver (for Arria V GT devices). This migration path is not shown in the Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Quartus Prime software Pin Planner.

Note: Except for Arria V GX A5 and A7, and Arria V GT C7 devices, all other Arria V GX and GT devices require a specific power-up sequence. If you plan to migrate your design from Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices, your design must adhere to the same required power-up sequence.



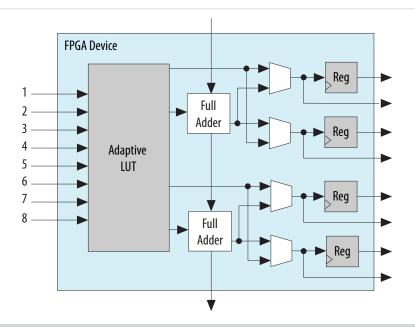
- Managing Device I/O Pins chapter, Quartus Prime Handbook Provides more information about vertical I/O migrations.
- Power Management in Arria V Devices
 Describes the power-up sequence required for Arria V GX and GT devices.

Adaptive Logic Module

Arria V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 7: ALM for Arria V Devices



You can configure up to 50% of the ALMs in the Arria V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Arria V Devices on page 20

Lists the embedded memory capacity for each device.



Variable-Precision DSP Block

Arria V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18, 27 x 27, and 36 x 36 bits natively
- A 64-bit accumulator
- Double accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Dynamic coefficients
- 18-bit internal coefficient register banks
- Enhanced independent multiplier operation
- Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Quartus Prime design software

Table 14: Variable-Precision DSP Block Configurations for Arria V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters	Two 18 x 18 with accumulate	1
Single-precision floating- point implementations	One 27 x 27	1
Very high precision fixed point implementations	One 36 x 36	2

You can configure each DSP block during compilation as independent three 9 x 9, two 18 x 18, or one 27×27 multipliers. Using two DSP block resources, you can also configure a 36×36 multiplier for high-precision applications. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.



		M20K		M20K M10K		MLAB		
Variant	Membe r Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)
Arria V ST	D3	_	_	1,729	17,290	3223	2,014	19,304
Allia V 31	D5	_	_	2,282	22,820	4253	2,658	25,478

Embedded Memory Configurations

Table 17: Supported Embedded Memory Block Configurations for Arria V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
MLAD	64 ⁽¹¹⁾	x10
	512	x40
	1K	x20
M20K	2K	x10
WIZOK	4K	x5
	8K	x2
	16K	x1
	256	x40 or x32
	512	x20 or x16
M10K	1K	x10 or x8
	2K	x5 or x4
	4K	x2
	8K	x1

Clock Networks and PLL Clock Sources

650 MHz Arria V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Altera's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note: To reduce power consumption, the Quartus Prime software identifies all unused sections of the clock network and powers them down.



⁽¹¹⁾ Available for Arria V GZ devices only.

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Arria V devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at less than 170 mW
- 10 Gbps transceivers at less than 165 mW
- 6 Gbps transceivers at less than 105 mW

Arria V transceivers are designed to be compliant with a wide range of protocols and data rates.

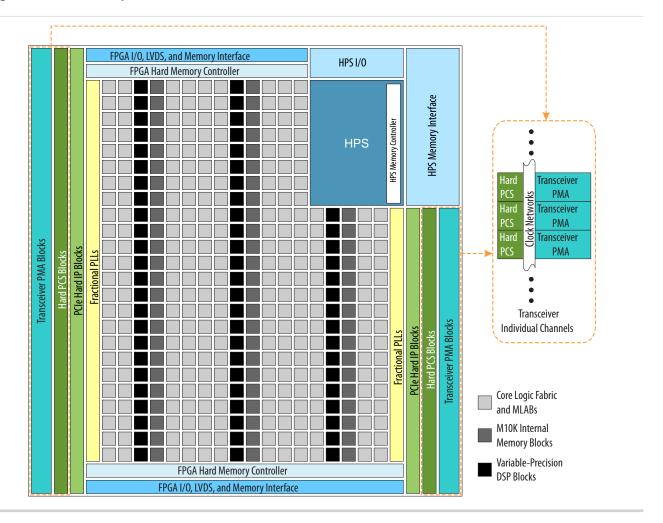
Transceiver Channels

The transceivers are positioned on the left and right outer edges of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

The following figures are graphical representations of a top view of the silicon die, which corresponds to a reverse view for flip chip packages. Different Arria V devices may have different floorplans than the ones shown in the figures.



Figure 11: Device Chip Overview for Arria V SX and ST Devices



PMA Features

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 20: PMA Features of the Transceivers in Arria V Devices

Features	Capability
Backplane support	 Arria V GX, GT, SX, and ST devices—Driving capability at 6.5536 Gbps with up to 25 dB channel loss Arria V GZ devices—Driving capability at 12.5 Gbps with up to 16 dB channel loss
Chip-to-chip support	 Arria V GX, GT, SX, and ST devices—Up to 10.3125 Gbps Arria V GZ devices—Up to 12.5 Gbps



PCS Support ⁽¹³⁾	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
PCIe Gen1 (x1, x2, x4, x8) PCIe Gen2 ⁽¹⁴⁾ (x1, x2, x4)	2.5 and 5.0	 Phase compensation FIFO Byte serializer 8B/10B encoder PIPE 2.0 interface to the core logic 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO PIPE 2.0 interface to the core logic
GbE	1.25	Phase compensation FIFOByte serializer8B/10B encoder	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO Rate match FIFO
XAUI ⁽¹⁵⁾	3.125	 Phase compensation FIFO Byte serializer 8B/10B encoder XAUI state machine for bonding four channels 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO XAUI state machine for realigning four channels Deskew FIFO circuitry
SDI	0.27 ⁽¹⁶⁾ , 1.485, 2.97	Phase compensation FIFO Byte serializer	Byte deserializerPhase compensation FIFO
GPON ⁽¹⁷⁾	1.25 and 2.5	byte serializer	1 mase compensation in O
CPRI ⁽¹⁸⁾	0.6144 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder TX deterministic latency 	 Word aligner 8B/10B decoder Byte deserializer Phase compensation FIFO RX deterministic latency



⁽¹³⁾ Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.

PCIe Gen2 is supported only through the PCIe hard IP.

⁽¹⁵⁾ XAUI is supported through the soft PCS.

⁽¹⁶⁾ The 0.27 Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.

 $^{^{\}left(17\right) }$ The GPON standard does not support burst mode.

⁽¹⁸⁾ CPRI data rates above 6.5536 Gbps, such as 9.8304 Gbps, are supported through the soft PCS.

SoC with HPS

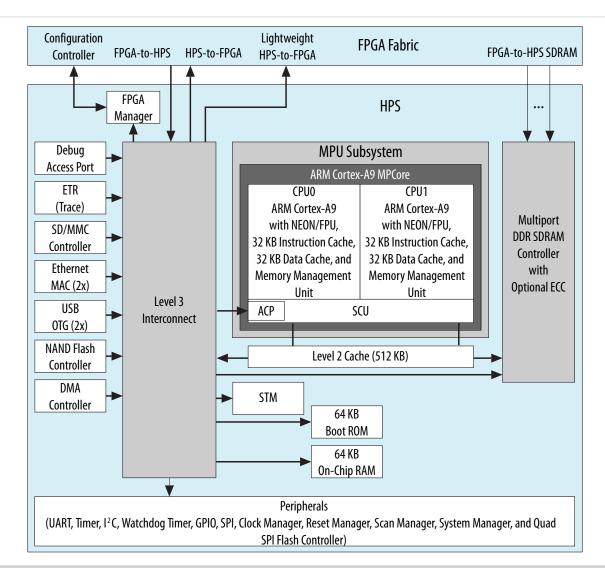
Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

Figure 12: HPS with Dual-Core ARM Cortex-A9 MPCore Processor





System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA[®]) Advanced eXtensible Interface (AXITM) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon[®] Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 533 MHz (1066 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.



You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Note: Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

- Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines
 Provides detailed information about power supply pin connection guidelines and power regulator sharing.
- Arria V GZ Device Family Pin Connection Guidelines
 Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Qsys system integration tool in the Quartus Prime software.

For software development, the ARM-based SoC devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Altera SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks®, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Altera sales team.

You can begin device-specific firmware and software development on the Altera SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

Altera Worldwide Sales Support

Dynamic and Partial Reconfiguration

The Arria V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA, PCS, and PCIe hard IP blocks with dynamic reconfiguration.



Mode	Data Width	Max Clock Rate (MHz)	Max Data I Rate (Mbps)	Decompression	Design Security F	Partial econfiguratio (20)	Remote System Update
	8 bits	125	_	Yes	Yes	_	
FPP	16 bits	125	_	Yes	Yes	Yes ⁽²¹⁾	Parallel flash loader
	32 bits ⁽²²⁾	100	_	Yes	Yes	_	
CvP (PCIe)	x1, x2, x4, and x8 lanes	_	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	_	_	_	_
Configuration	16 bits	125	_	Yes	Yes	Yes (21)	Parallel flash loader
via HPS	32 bits	100	_	Yes	Yes	_	rafanei nasn loadei

Instead of using an external flash or ROM, you can configure the Arria V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Arria V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Note: Although Arria V GZ devices support PCIe Gen3, you can use only PCIe Gen1 and PCIe Gen2 for CvP configuration scheme.

Related Information

Configuration via Protocol (CvP) Implementation in Altera FPGAs User Guide Provides more information about CvP.

Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Arria V devices consume less power than previous generation Arria V FPGAs:

- Total device core power consumption—less by up to 50%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Arria V devices contain several hard IP blocks, including PCIe Gen1, Gen2, and Gen3, GbE, SRIO, GPON, and CPRI protocols, that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.



⁽²⁰⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

⁽²¹⁾ Supported at a maximum clock rate of 62.5 MHz.

⁽²²⁾ Arria V GZ only

Document Revision History

Date	Version	Changes
December 2015	2015.12.21	 Updated RoHS and optional suffix information in sample ordering code and available options diagrams for Arria V GX and GT devices. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
January 2015	2015.01.23	 Updated package dimension for Arria V GZ H780 package from 29 mm to 33 mm. Updated dual-core ARM Cortex-A9 MPCore processor maximum frequency from 800 MHz to 1.05 GHz.
December 2013	2013.12.26	 10-Gbps Ethernet (10GbE) PCS and Interlaken PCS are for Arria V GZ only. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Added link to Altera Product Selector for each device variant. Added leaded package options. Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F896 package from 170 to 250. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1152 package from 350 to 385. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1517 package from 528 to 540. Corrected LVDS Transmitter for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 devices from 121 to 120. Added links to Altera's External Memory Spec Estimator tool to the topics listing the external memory interface performance. Added x2 for PCIe Gen3, Gen 2, and Gen 1.
August 2013	2013.08.19	 Removed the note about the PCIe hard IP on the right side of the device in the F896 package of the Arria V GX variant. These devices do not have PCIe hard IP on the right side. Added transceiver speed grade 6 to the available options of the Arria V SX variant. Corrected the maximum LVDS transmitter channel counts for the Arria V GX A1 and A3 devices from 68 to 67. Corrected the maximum FPGA GPIO count for Arria V ST D5 devices from 540 to 528.



Date	Version	Changes
June 2013	2013.06.03	Removed statements about contacting Altera for SFF-8431 compliance requirements. Refer to the Transceiver Architecture in Arria V Devices chapter for the requirements.
May 2013	2013.05.06	 Moved all links to the Related Information section of respective topics for easy reference. Added link to the known document issues in the Knowledge Base. Updated the available options, maximum resource counts, and per package information for the Arria V SX and ST device variants. Updated the variable DSP multipliers counts for the Arria V SX and ST device variants. Clarified that partial reconfiguration is an advanced feature. Contact Altera for support of the feature. Added footnote to clarify that MLAB 64 bits depth is available only for Arria V GZ devices. Updated description about power-up sequence requirement for device migration to improve clarity.
January 2013	2013.01.11	 Added the L optional suffix to the Arria V GZ ordering code for the – I3 speed grade. Added a note about the power-up sequence requirement if you plan to migrate your design from the Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices.
November 2012	2012.11.19	 Updated the summary of features. Updated Arria V GZ information regarding 3.3 V I/O support. Removed Arria V GZ engineering sample ordering code. Updated the maximum resource counts for Arria V GX and GZ. Updated Arria V ST ordering codes for transceiver count. Updated transceiver counts for Arria V ST packages. Added simplified floorplan diagrams for Arria V GZ, SX, and ST. Added FPP x32 configuration mode for Arria V GZ only. Updated CvP (PCIe) remote system update support information. Added HPS external memory performance information. Updated template.
October 2012	3.0	 Added Arria V GZ information. Updated Table 1, Table 2, Table 3, Table 14, Table 15, Table 16, Table 17, Table 18, Table 19, Table 20, and Table 21. Added the "Arria V GZ" section. Added Table 8, Table 9 and Table 22.



Date	Version	Changes
July 2012	2.1	 Added –I3 speed grade to Figure 1 for Arria V GX devices. Updated the 6-Gbps transceiver speed from 6.553 Gbps to 6.5536 Gbps in Figure 3 and Figure 1.
June 2012	2.0	 Restructured the document. Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. Added Table 1, Table 3, Table 12, Table 15, and Table 16. Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 13, Table 14, and Table 19. Updated Figure 1, Figure 2, Figure 3, Figure 4, and Figure 8. Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. Text edits throughout the document.
February 2012	1.3	 Updated Table 1–7 and Table 1–8. Updated Figure 1–9 and Figure 1–10. Minor text edits.
December 2011	1.2	Minor text edits.
November 2011	1.1	 Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–6, Table 1–7, Table 1–9, and Table 1–10. Added "SoC FPGA with HPS" section. Updated "Clock Networks and PLL Clock Sources" and "Ordering Information" sections. Updated Figure 1–5. Added Figure 1–6. Minor text edits.
August 2011	1.0	Initial release.

